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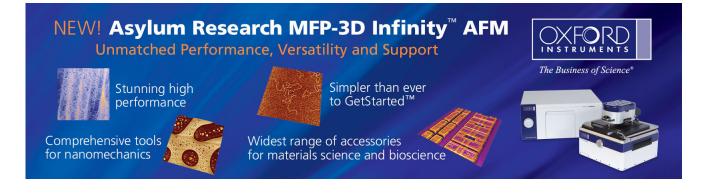
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## Near-field optical microscopy and scanning Kelvin microscopy studies of V-defects on AlGaN/GaN films

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Al<sub>x</sub>Ga<sub>1-x</sub>N thin film was grown on undoped GaN/sapphire (0001) substrate by metalorganic chemical vapor deposition. V-defects were directly observed by atomic force microscopy (AFM) with various size of  $0.5-2 \ \mu m$  in diameter. In a previous study, the microphotoluminescence spectra showed an extra peak ( $I_{v}$ =350 nm) inside the V-defect besides the near-band-edge emission ( $I_{obe}$ =335 nm). To achieve better spatial resolution, we used near-field scanning optical microscopy (NSOM) and scanning Kelvin-force microscopy (SKM) to probe the V-defect in detail. The NSOM spectra showed that the intensity of the  $I_v$  band increased gradually from V-defect edges to its center, while  $I_{\rm nbe}$  remained unchanged. Besides, the SKM measurements revealed that the Fermi level decreased from the flat region to V-defect center by about 0.2 eV. These results suggest that the  $I_{\nu}$ band could be related to shallow acceptor levels, likely resulting from  $V_{\text{Ga}}$  defects. © 2004 American Institute of Physics. [DOI: 10.1063/1.1799248]

Nitride alloys (GaN, InGaN, and AlGaN) are promising wide band-gap semiconductors which have applications in both electronic devices operating at high temperature, high frequency, and high power and optical devices such as lightemitting diodes in the blue-green and ultraviolet wavelength regions.<sup>1,2</sup> However, for  $In_xGa_{1-x}N$  and  $Al_xGa_{1-x}N$  layers grown on GaN, an increase in In and Al compositions may inevitably cause misfit strains in films. Beyond a critical thickness, several structural defects such as misfit dislocations, stacking faults, V-shape pits, etc., are generated by plastic relaxation.<sup>3</sup> According to the report by Wu et al., the V-shape pits caused asymmetry in photoluminescence (PL) spectra with a low-energy shoulder.<sup>4</sup> Our previous micro-PL studies also showed similar results.<sup>5</sup> Nevertheless, these structural defects are not necessarily detrimental to their optical and electronic properties, especially for AlGaN films. In this letter, we present experimental results of Al<sub>0.16</sub>Ga<sub>0.84</sub>N by showing near-field images, electric potentials, and PL spectra of V-pits. Near-field scanning optical microscopy photoluminescence (NSOM-PL) and scanning Kelvin-force microscopy (SKM) were used to investigate the photoexcited carrier recombination mechanisms and spatial distribution of the PL spectrum. Then an energy diagram is proposed to interpret the observed transition and distribution behavior of photoexcited carriers.

The Al<sub>0.16</sub>Ga<sub>0.84</sub>N film was grown on the (0001) sapphire substrate at 1120 °C by using low-pressure metalorganic vapor phase epitaxy. Prior to growth, a GaN nucleation layer of 250 Å was first deposited at 520° C, followed by a 2-µm-thick GaN buffer layer at 1120 °C. Then, the AlGaN layer about 0.8  $\mu$ m thick was grown on GaN buffer layer at the same temperature. The Al, Ga, and N precursors were trimethylaluminum, trimethylgallium, and ammonia with flow rates of 20, 10, 5000 sccm, respectively. The electron mobility and carrier concentration were determined by Hall measurements to be 131 cm<sup>2</sup>/V s and  $1 \times 10^{18}$  cm<sup>-3</sup>, respectively. The x-ray diffraction showed the full width at half maximum (FWHM) about 370 arcsec that is similar to the report of Choi et al.°

For NSOM-PL measurements, an atomic force microscopy (AFM, Solver P47H)-based system combined with NSOM shear-force scanner head (Solver SNC080) was employed to obtain shear-force surface topography and near field spectra. We used illumination mode, by coupling a He-Cd laser (Omnichrome 2056) operating at 325 nm with 25 mW into the single-mode quartz fiber tip that is prepared by chemical eaching with HF solution, to excite the sample. The tip output power was about 100  $\mu$ W and the luminescence signals were then collected by a far field micro-UV lens and couped into a multimode fiber and sent to the monochromator (ARC-500) and photomultiplier tube (Hamamatsu R955) for detection. The tip radius of curvature is less than 100 nm as determined by SEM. It is coated with Pt of  $\sim$ 50 nm thickness by an ion sputter (Hitachi E-1010) in order to confine laser illumination within a very small pinhole. The distance between the fiber tip and sample surface, which was controllable and adjustable by the shear-force feedback mechanism, was usually maintained at 10-100 nm. For surface potential measurements, the SKM mode of AFM <sup>7,8</sup> was employed for which the tip has a radius of curvature  $\sim 10$  nm.

The AlGaN films grown on GaN usually contains various defects including V-shape pits. In general, the V-pit size distribution ranges from about 0.5 to 2  $\mu$ m. The shear-force image in Fig. 1(a) shows one such pit of width  $\sim$ 1.5  $\mu$ m that is common in AlGaN. Along one diagonal line, we measured NSOM-PL spectra at five different spots near or inside the pit except the O point on flat region, as shown in Fig. 1(b). At the O point, only the near-band-edge transition  $(I_{nbe})$  at 335 nm is observed. From A to D points, a broad-peak  $(I_v)$  at 350 nm appears and its intensity increases from pit edge to pit center, while  $I_{\rm nbe}$  intensity remains essentially the same. The inset of Fig. 1(b) shows the relative intensity of  $I_{nbe}$  and  $I_v$  normalized to  $I_{nbe}$  at the O point (flat region). In other reports<sup>4,9–12</sup> the V-pit may be interpreted as the In-rich region in InGaN or Al-rich region in AlGaN. However, Al-rich or

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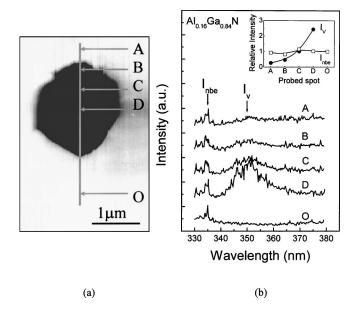
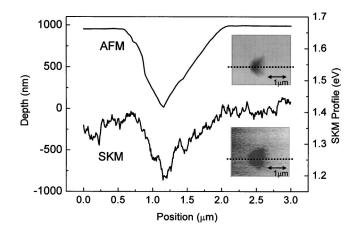


FIG. 1. (a) NSOM topography image of V-shape pit and measurement spots. (b) Near-field PL spectra taken from each spot. The inset shows that nearband-edge emission intensity changes very little but the V-pit related broad peak increased rapidly toward the pit center.

phase separation phenomena do not occur in our sample, because the  $I_{nbe}$  peak position does not change at all measured spots. Regarding the origin of the  $I_v$  peak in the V-shape pit, it may be related to the stress due to lattice mismatch between AlGaN and GaN films. Then, the piezoelectric field effect would cause the redshift of  $I_{nbe}$  peak position in V-shape pit of different size. However, our NSOM-PL results show insignificant shift of  $I_{nbe}$  so that it is irrelevant to the pit size. Based on our results, it is proposed that the  $I_v$  may be attributed to defect level transition.

In order to investigate the electrical potential distribution across the V-shape pit, the SKM was carried out on the same pit as that measured by NSOM. The tip–sample separation was kept at 50 nm in all measurements. As shown in Fig. 2, the AFM cross-section profile shows such a pit with ~1.5  $\mu$ m width and 1  $\mu$ m depth. From the operational principle of SKM, an oscillating voltage  $V_{applied}=V_1 \sin(\omega t)$  is applied directly to the AFM tip and combines with a dc bias voltage  $V_0$  to detect the local surface potential. Then, the tip will feel a force of



This aFIG. 2. The upper line show the AFM profile of V pit about 1.5  $\mu$ m width and 1  $\mu$ m depth. The lower line shows surface potential distribution.

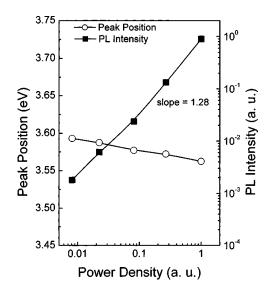


FIG. 3. Power dependence micro-PL results of peak position and intensity at 350 nm.

$$F_{z}(\omega) = -\left[(V_{0} - \varphi_{x,v})V_{1}\sin(\omega t)\right](\partial C/\partial z)$$

where  $\varphi_{x,y}$  is the surface potential of sample at position (x, y)and  $(\partial C/\partial z)$  is the vertical derivative of the tip-sample capacitance. The dc bias voltage is adjusted to cancel out the sample potential, i.e.  $(V_0 - \varphi_{x,y}) = 0$ , so that the tip feels no force. Then,  $\varphi_{x,y}$  corresponds to the work function difference between the tip metal and sample, i.e.,  $\varphi_{x,y} = \varphi_{tip} - \varphi_{AlGaN}$ , where  $\varphi_{tip}$  is the work function of tip, and  $\varphi_{AlGaN} = \chi_{AlGaN}$  $+\xi$  is the difference between the Fermi-level and vacuum level which depends on the thickness of AlGaN layer.<sup>13</sup> The  $\chi_{AIGaN}$  is the electron affinity and  $\xi$  is the energy difference between the Fermi level and conduction band. Thus, one can obtain the Fermi level at any position from  $\varphi_{x,y}$ . As shown in Fig. 2, the surface potential profile decreases from the flat region to V-pit center, and the largest potential difference is about  $0.2\pm0.025$  V. These results indicated that the Fermi level inside the pit is shifted toward the valence band, reflecting characteristics of acceptor type defects. Under thermal equilibrium condition, the Fermi level is assumed to be pinned at the same position, so that the band will bend upwardly inside the V-pit. Because negative charges trapped in acceptor levels and positive charges will made band bending to maintain charge neutrality. According to Jenkins *et al.* and Tansley *et al.*,  $^{14,15}$  two acceptor type levels existed below the intrinsic Fermi level in GaN, one was the antisite  $(Ga_N)$  and another was Ga vacancy (namely  $V_{Ga}$ ) at 0.7–1.1 eV and 136 meV above the valence band, respectively. We tentatively attribute the  $I_v$  broad peak to the  $V_{\text{Ga}}$ -related transition, because the deep level of Ga<sub>N</sub> cannot account for this photon energy. Jeong et al.,<sup>10,16–18</sup> also used a similar reason to interpret the raised lower-energy shoulder in InGaN/GaN samples. Furthermore, we observed that the  $I_v$  peak intensity increases the excitation power with a slope of  $\sim 1.28$  and its peak shows a small redshift of  $\sim$ 30 meV in Fig. 3. This suggests that the  $I_v$  transition should be a free-to-bound transition.

Besides, both NSOM-PL spectra and SKM surface potential profile clearly show the  $V_{Ga}$ -related defect distribution decreasing from the pit center to outer region. The dense population of  $V_{Ga}$  not only causes the Fermi level to be lower than the surrounding region, but also provides more

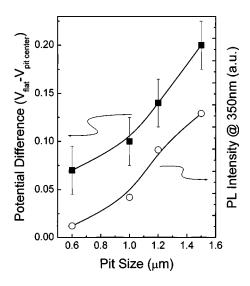


FIG. 4. Closed-square line shows the difference of the surface potential between the flat region and center of pit, indicating that the Fermi level is lower in the larger pit case. Simultaneously, the open-circle line also increased with identical trend.

recombination centers by allowing electron relaxation from shallow donor. To establish the relationship between the  $I_v$ peak intensity and pit size, we show in Fig. 4 the SKM potential difference between the pit center and the flat region and the PL intensity for different pit size. The  $I_v$  emission intensity is directly proportional to V-shape pit size in which  $V_{Ga}$  density is obviously larger. This also supports our arguments from NSOM results.

Based on the available data, we attempt to propose a schematic energy diagram. The familiar shallow donor level is responsible for the near-band-edge transition. Inside the V-shape pit, another level located at  $\sim 136$  eV above the valence band contributes to the  $I_v$  peak. The Fermi level at the pit-center was lower than the surrounding region and carriers tend to flow to pit region for radiative recombination.

In summary, although there are only a few reports<sup>10,19</sup> about spectroscopic study of V-shape pit on InGaN and GaN by using NSOM, there is no report on AlGaN yet due to poor signal collection efficiency in the UV region. We have developed an UV excitation NSOM system different from cathodoluminescence type that avoids high energy electron damage to the sample<sup>20</sup> and still provided the same spatial resolution

to investigate the V-shape pit on the Al<sub>0.16</sub>Ga<sub>0.84</sub>N film. The results revealed the extra defect levels inside V-shape pits. In addition, the lowered Fermi level in the pit region from SKM measurements indicated new acceptor-like levels below the Fermi level. These results suggested that deep levels inside the V-pit are likely attributed to  $V_{Ga}$ -related defects. From SKM and PL studies, the  $V_{Ga}$  population is responsible for the PL intensity of different pit size and the pit formation is closely associated with  $V_{Ga}$  in AlGaN.

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- <sup>1</sup>H. Morkoc, *Nitride Semiconductors and Devices* (Springer, Heidelberg, 1999).
- <sup>2</sup>S. Nakamura, Science **281**, 956 (1998).
- <sup>3</sup>H. K. Cho, J. Y. Lee, C. S. Kim, G. M. Yang, N. Sharma, and C. J. Humphreys, J. Cryst. Growth **231**, 466 (2001).
- <sup>4</sup>X. H. Wu, C. R. Elsass, A. Abare, M. Mack, S. Keller, P. M. Petroff, S. P. DenBaars, J. S. Speck, and S. J. Rosner, Appl. Phys. Lett. **72**, 692 (1998).
  <sup>5</sup>H. Y. Huang, C. S. Ku, W. C. Ke, N. E. Tang, J. M. Peng, W. K. Chen, W.
- H. Chen, and M. C. Lee, J. Appl. Phys. 95, 2172 (2004).
- <sup>6</sup>S. C. Choi, J.-H. Kim, J. Y. Choi, K. J. Lee, K. Y. Lim, and G. M. Yang, J. Appl. Phys. 87, 172 (2000).
- <sup>7</sup>T. Mizutani, M. Arakawa, and S. Kishimoto, IEEE Electron Device Lett. **18**, 423 (1997).
- <sup>8</sup>T. Usunami, M. Arakawa, S. Kishimoto, T. Mizutani, T. Kagawa, and H. Iwamura, Jpn. J. Appl. Phys., Part 1 **37**, 1522 (1998).
- <sup>9</sup>Y. Chen, T. Takeuchi, H. Amano, I. Akasaki, N. Yamada, and Y. Kaneko, Appl. Phys. Lett. **72**, 710 (1998).
- <sup>10</sup>M. S. Jeong, Y.-W. Kim, J. O. White, E.-K. Suh, M. G. Cheong, C. S. Kim, C.-H. Hong, and H. J. Lee, Appl. Phys. Lett. **79**, 3440 (2001).
- <sup>11</sup>G. Pozina, J. P. Bergman, B. Monemar, T. Takeuchi, H. Amano, and I. Akasaki, J. Appl. Phys. 88, 2677 (2000).
- <sup>12</sup>B. Pè cz, Zs. Makkai, M. A. di Forte-Poisson, F. Huet, and R. E. Dunin-Borkowski, Appl. Phys. Lett. **78**, 1529 (2001).
- <sup>13</sup>G. Koley and M. G. Spencer, J. Appl. Phys. **90**, 337 (2001).
- <sup>14</sup>D. W. Jenkins and J. D. Dow, Phys. Rev. B **39**, 3317 (1989).
- <sup>15</sup>T. L. Tansley and R. J. Egan, Phys. Rev. B 45, 10942 (1992).
- <sup>16</sup>J. Elsner, R. Jones, M. I. Heiggie, P. K. Sitch, M. Haugk, Th. Freunheim, S. Oberg, and P. R. Briddon, Phys. Rev. B 58, 12571 (1998).
- <sup>17</sup>X. Li, P. W. Bohn, J. Kim, J. O. White, and J. J. Coleman, Appl. Phys. Lett. **76**, 3031 (2000).
- <sup>18</sup>S. H. Yang, K. S. Nahn, Y. B. Hahn, Y. S. Lee, M. S. Jeong, and E. -K. Suh, J. Korean Phys. Soc. **36**, 1821 (2000).
- <sup>19</sup>P. A. Crowell, D. K. Young, S. Keller, E. L. Hu, and D. D. Awschalom, Appl. Phys. Lett. **72**, 927 (1998).
- <sup>20</sup>J. L. Bubendorff, D. Pastrc, and M. Troyon, J. Microsc. **199**, 191 (2000).